

Analog Signal Processor (ASP) for CD players

Overview

The LA9230M and LA9231M are analog signal processing and servo control bipolar ICs designed for use in compact disc players; a compact disc player can be configured by combining these ICs, a CD-DSP such as the LC78620E, and a small number of additional components. The differences between the LA9230M and the LA9231M are that the LA9231M: (1) has a focus search time that is four times faster; (2) has an additional capacitor pin for focus search smoothing; (3) and can disable output of the track-kick signal during EF balance adjustment.

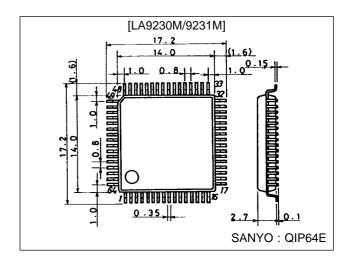
Functions

I/V amplifier, RF amplifier (with AGC), SLC, APC, FE, TE (with VCA and auto-balance function), focus servo amplifier (with offset cancellation function), tracking servo amplifier (with offset cancellation function), spindle servo amplifier (with gain switching function), sled servo amplifier (with off function), focus detection (DRF, FZD), track detection (HFL, TES), defect detection, and shock detection.

Package Dimensions

unit: mm

3159-QIP64E



Features

The following automatic adjustment functions are built in.

- · Focus offset auto cancel
- · Tracking offset auto cancel
- EF balance auto adjustment
- RF level AGC function
- Tracking servo gain RF level following function

Specifications

Maximum Ratings at Ta = 25 °C, Pins 22, 45 = GND

Parameter	Symbol	Conditions	Ratings	Unit
Maximum supply voltage	Vsup max	Pin 56, 64	7	V
Allowable power dissipation	Pd max		350	mW
Operating temperature	Topr		−25 to +75	∘C
Storage temperature	Tstg		-40 to +150	°C

Operating Conditions at Pins 22, 45 = GND

Parameter	Symbol	Conditions	Ratings	Unit
Recommended supply voltage	V _{CC}		5	V
Operating supply voltage	V _{CC} op		3.6 to 5.5	V

Operating Characteristics at Ta = 25 $^{\circ}$ C, Pins 22, 45 = GND, $V_{\rm CC}$ (pins 56, 64) = 5 V

Parameter	Symbol	Conditions	min	typ	max	Unit
Current drain	Icco	V _{CC} 1 (pin 64) + V _{CC} 2 (pin 56)	22	32	42	mA
Reference voltage	Vref	VR	2.3	2.5	2.7	V
[Interface]						
CE-Vth	CEvth	CE		0.8		V
CL-Vth	CLvth	CL		0.8		V
DAT-Vth	DATvth	DAT		0.8		V
Maximum CL frequency	CLmax		500			kHz
[RF amplifier]	•					
RFSM no signal voltage	RFSMo		1.35	1.60	1.85	V
Minimum gain	RFSM _G min	FIN1, FIN2 : 1 MΩ-input, PH1 = 4 V freq = 200 kHz, RFSM	-14.0	-12.5	-11.0	dB
[Focus amplifier]	<u>'</u>					
FDO gain	FD _G	FIN2 : 1 MΩ-input, FDO	3.5	5.0	6.5	dB
FDO offset	FDost	Difference from reference voltage, servo on	-170	0	+170	mV
Off time offset	FDofost	Difference from reference voltage, servo off	-40	0	+40	mV
Offset adjustment step	FDstep	FDO		50		V
F search voltage H	FSmax	FDO		0.8		V
F search voltage L	FSmin	FDO		-0.8		V
[Tracking amplifier]		,				
TE gain MAX	TE _G max	f = 10 kHz, E: 1 MΩ-input, PH1 = 4 V	5.0	6.5	8.0	dB
TE gain MIN	TE _G min	f = 10 kHz, E: 1 MΩ-input, PH1 = 1 V	-0.5	+1.8	+4.0	dB
TE-3 dB	TEfc	E: 1 MΩ-input		60		kHz
TO gain	TO _G	$TH \to TO$ gain, THLD mode	4.0	6.0	8.0	dB
TGL offset	TGLost	Servo on, TGL = H, TO	-250	0	+250	mV
TGH offset	TGHost	TGL = L, difference from TGL offset, TO	-50	0	+50	mV
THLD offset	THLDost	THLD mode, difference from TGL offset, TO	-50	0	+50	mV
Off 1 offset	OFF1ost	TOFF = H	-50	0	+50	mV
Off 2 offset	OFF2ost	TOF2 off (IF)	-50	0	+50	mV
Offset adjustment step	TOstep	ТО		60		mV
Balance range H	BAL-H	Δ gain E/F input, TB = 5 V		3.5		dB
Balance range L	BAL-L	Δ gain E/F input, TB = 0 V		-3.5		dB
TOFF-VTH	TOFFvth		1.0	2.5	3.0	V
TGL-VTH	TGLvth		1.0	2.5	3.0	V
[PH]	•					
No signal voltage	PHo	Difference from RFSM	-0.85	-0.65	-0.45	V
[BH]	•	·		•		
No signal voltage	BHo	Difference from RFSM	0.45	0.65	0.85	V
[DRF]	•			•		
Detection voltage	DRFvth	Difference from VR at RFSM	-0.60	-0.35	-0.20	V
Output voltage H	DRF-H		4.5	4.9		V
Output voltage L	DRF-L			0	+0.5	V
[FZD]						
Detection voltage 1	FZD1	FE, difference from VR	0	+0.2		V
Detection voltage 2	FZD2	FE, difference from VR		0		V

Continued from preceding page.

	Parameter	Symbol	Conditions	min	typ	max	Unit
Output voltage H HFL-H Output voltage L HFL-L	[HFL]						
Detection voltage L	Detection voltage	HFLvth	Difference from VR at RFSM	-0.35	-0.2	-0.05	V
TES Detection voltage LH	Output voltage H	HFL-H		4.5	4.9		
Detection voltage LH	Output voltage L	HFL-L			0	+0.5	V
Detection voltage HL	[TES]	•					
Output voltage H TES-H 4.5 4.9 V Qutput voltage L TES-L 0 +0.5 V Upp TES-L Difference from JP* = 0 V, JP* = 0 V at JP* = 0 V, 0.35 0.5 0.65 V Output voltage L JP-L Difference from JP* = 0 V, JP* = 0 V at JP* = 5 V, JP* = 5 V, JP* = 0.05 -0.65 -0.5 -0.35 V Image: Spindle amplifier] Offset 2 SPD12ost Difference from VR at SPD, 12 cm mode -40 0 +40 mV Offset 8 SPD8ost Difference from VR at SPD, 8 cm mode -40 0 +40 mV Offset 8 SPD6ost Difference from VR at SPD, 9 cFF mode -30 0 +30 mV Output voltage H12 SPD-H12 Difference from VR at SPD, 0 cFF mode -30 0 +30 mV Output voltage H8 SPD-H12 Difference from Offset-12, 12 cm mode -1.25 -1.0 -0.75 V Output voltage H8 SPD-H8 Difference from offset-12, 12 cm mode -1.25 -1.0 -0.75 V	Detection voltage LH	TES-LH	TESI, difference from VR	-0.15	-0.10	-0.05	V
Output voltage L TES-L 0 +0.5 V [JP] Output voltage H JP-H Difference from JP* = 0 V, JP* = 0 V at JP* = 0 V, DP* = 0 V, DP* = 0 V, DP* = 0 V at JP* = 5 V, DP* = 0 V, DP* =	Detection voltage HL	TES-HL	TESI, difference from VR	0.05	0.10	0.15	V
JP Output voltage H	Output voltage H	TES-H		4.5	4.9		V
Output voltage H JP-H Difference from JP* = 0 V, JP⁻ = 0 V at JP* = 0 V, JP⁻ = 6 V, TO 0.35 0.5 0.65 V Output voltage L JP-L Difference from JP* = 0 V, JP⁻ = 0 V at JP* = 6 V, JP⁻ = 6 V, JP⁻ = 0 V, TO -0.65 -0.5 -0.35 V (Spindle amplifier) Offset 12 SPD12ost Difference from VR at SPD, 12 cm mode -40 0 +40 mV Offset 8 SPD8ost Difference from VR at SPD, 8 cm mode -40 0 +40 mV Offset off SPD6 Difference from VR at SPD, 0FF mode -30 0 +30 mV Output voltage H12 SPD-H12 CV* = 5 V, CV* = 0 V 0.75 1.0 1.25 V Output voltage L12 SPD-H12 Difference from offset-12, 12 cm mode -1.25 -1.0 -0.75 V Output voltage H8 SPD-H8 Difference from offset-8, 8 cm mode 0.35 0.5 0.65 V [Sled amplifier] SLEQ offset SLEQ st Difference from TO at SLEQ -30 0 +30 mV Of	Output voltage L	TES-L			0	+0.5	V
Output voltage L JP- Image: Second process of the proce	[JP]						
Spindle amplifier	Output voltage H	JP-H	$JP^- = 5 \text{ V, TO}$	0.35	0.5	0.65	V
Offset 12 SPD12ost Difference from VR at SPD, 12 cm mode -40 0 +40 mV Offset 8 SPD8ost Difference from VR at SPD, 8 cm mode -40 0 +40 mV Offset off SPDof Difference from VR at SPD, OFF mode -30 0 +40 mV Output voltage H12 SPD-H12 Difference from offset-12, 12 cm mode CV* = 5 V, CV* = 0 V 0.75 1.0 1.25 V Output voltage L12 SPD-H12 Difference from offset-12, 12 cm mode CV* = 5 V, CV* = 5 V -1.25 -1.0 -0.75 V Output voltage H8 SPD-H8 SPD-H8 CV* = 5 V, CV* = 5 V -1.25 -1.0 -0.75 V Gled amplifier] SEC Offset SLEQ SED Difference from offset-8, 8 cm mode CV* = 5 V, CV* = 0 V 0.35 0.5 0.65 V SLEQ offset SLEQ SLOST Difference from TO at SLEQ -30 0 +30 mV Offset SLD SLDost SLEQ = VR, difference from VR -10 0 +40 mV Off VTH SLOF S	Output voltage L	JP-L	· ·	-0.65	-0.5	-0.35	V
Offset 8 SPD8ost Difference from VR at SPD, 8 cm mode -40 0 +40 mV Offset off SPDof Difference from VR at SPD, OFF mode -30 0 +30 mV Output voltage H12 SPD-H12 Difference from offset-12, 12 cm mode CV⁺ = 5 V, CV⁻ = 0 V 0.75 1.0 1.25 V Output voltage L12 SPD-L12 Difference from offset-12, 12 cm mode CV⁺ = 5 V, CV⁻ = 0 V -1.25 -1.0 -0.75 V Output voltage H8 SPD-H8 Difference from offset-8, 8 cm mode CV⁺ = 5 V, CV⁻ = 0 V 0.35 0.5 0.65 V [Sled amplifier] SLEQ offset SLEQost Difference from TO at SLEQ -30 0 +30 mV Offset SLD SLDost SLEQ = VR, difference from VR -100 0 +40 mV Offset off SLDof Off mode -40 0 +40 mV Off VTH SLOFvth SLC 2.25 2.5 2.75 V [Shock] No signal voltage SClo SCl, difference from VR	[Spindle amplifier]						
Offset off SPDof Difference from VR at SPD, OFF mode −30 0 +30 mV Output voltage H12 SPD-H12 Difference from offset-12, 12 cm mode CV+ 5 V, CV− 0 V 0.75 1.0 1.25 V Output voltage L12 SPD-L12 Difference from offset-12, 12 cm mode CV+ 0 V, CV− 5 V −1.25 −1.0 −0.75 V Output voltage H8 SPD-H8 Difference from offset-8, 8 cm mode CV+ 5 V, CV− 6 V 0.35 0.5 0.65 V [Sled amplifier] SLEQ offset SLEQost Difference from TO at SLEQ −30 0 +30 mV Offset SLD SLDost SLEQ = VR, difference from VR −100 0 +100 mV Offset off SLDof Off mode −40 0 +40 mV Off VTH SLOFVth SLOF 1.0 1.4 2.0 V [Shock] No signal voltage SLC SLC 2.25 2.5 2.75 V [Shock] No signal voltage SCIo SCI, difference from VR 60 100	Offset 12	SPD12ost	Difference from VR at SPD, 12 cm mode	-40	0	+40	mV
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	Offset 8	SPD8ost	Difference from VR at SPD, 8 cm mode	-40	0	+40	mV
Output voltage H12 SPD-H12 CV* = 5 V, CV⁻ = 0 V 0.75 1.0 1.25 V Output voltage L12 SPD-L12 Difference from offset-12 , 12 cm mode CV⁺ = 0 V, CV⁻ = 5 V −1.25 −1.0 −0.75 V Output voltage H8 SPD-H8 Difference from offset-8, 8 cm mode CV⁺ = 5 V, CV⁻ = 0 V 0.35 0.5 0.65 V [Sled amplifier] SLEQ offset SLEQost Difference from TO at SLEQ −30 0 +30 mV Offset SLD SLDost SLEQ = VR, difference from VR −100 0 +100 mV Offset off SLDof Off mode −40 0 +40 mV Off VTH SLOF SLOF 1.0 1.4 2.0 V [SLC] No signal voltage SLCo SLC 2.25 2.5 2.75 V [Shock] No signal voltage SClo SCl, difference from VR −40 0 +40 mV Detection voltage H SClvthL SCl, difference from VR	Offset off	SPDof	Difference from VR at SPD, OFF mode	-30	0	+30	mV
Output voltage L12 SPD-L12 CV* = 0 V, CV^ = 5 V -1.25 -1.0 -0.75 V Output voltage H8 SPD-H8 Difference from offset-8, 8 cm mode CV* = 5 V, CV^ = 0 V 0.35 0.5 0.65 V [Sled amplifier] SLEQ offset SLEQost Difference from TO at SLEQ -30 0 +30 mV Offset SLD SLDost SLEQ = VR, difference from VR -100 0 +40 mV Offset off SLDof Off mode -40 0 +40 mV Off VTH SLOFvth SLOF 1.0 1.4 2.0 V [SlCC] No signal voltage SLCo SLC 2.25 2.5 2.75 V [Shock] No signal voltage SCIO SCI, difference from VR -40 0 +40 mV Detection voltage H SCIvthH SCI, difference from VR -40 0 +40 mV [DEF] Detection voltage DEFvth S.5	Output voltage H12	SPD-H12	· · · · · · · · · · · · · · · · · · ·	0.75	1.0	1.25	V
Seed amplifier	Output voltage L12	SPD-L12		-1.25	-1.0	-0.75	V
SLEQ offset SLEQost Difference from TO at SLEQ -30 0 +30 mV Offset SLD SLDost SLEQ = VR, difference from VR -100 0 +100 mV Offset off SLDof Off mode -40 0 +40 mV Off VTH SLOF vth SLOF 1.0 1.4 2.0 V [SLC] No signal voltage SLCo SLC 2.25 2.5 2.75 V [Shock] No signal voltage SClo SCI, difference from VR -40 0 +40 mV Detection voltage H SClvthH SCI, difference from VR 60 100 140 mV [DEF] Detection voltage DEFvth S.5 V and DEF is detected and LF2 voltage when RFSM = 3.5 V 0.35 0.50 V Output voltage H DEF-H 4.5 4.9 V Output voltage L DEF-L 0 +0.5 V [APC] Reference voltage LDS L	Output voltage H8	SPD-H8		0.35	0.5	0.65	V
Offset SLD SLDost SLEQ = VR, difference from VR -100 0 +100 mV Offset off SLDof Off mode -40 0 +40 mV Off VTH SLOFvth SLOF 1.0 1.4 2.0 V [SLC] No signal voltage SLCo SLC 2.25 2.5 2.75 V [Shock] No signal voltage SCIo SCI, difference from VR -40 0 +40 mV Detection voltage H SCIvthH SCI, difference from VR 60 100 140 mV [DEF] Detection voltage L SCIvthL SCI, difference from VR -140 -100 -60 mV [DEF] Difference between LF2 voltage when RFSM = 3.5 V 0.20 0.35 0.50 V Output voltage H DEF-H DEF-H 4.5 4.9 V Output voltage L DEF-L DEF-L 0 +0.5 V [APC] Reference voltag	[Sled amplifier]	•	-				
Offset off SLDof Off mode -40 0 +40 mV Off VTH SLOFvth SLOF 1.0 1.4 2.0 V [SLC] No signal voltage SLCo SLC 2.25 2.5 2.75 V [Shock] No signal voltage SClo SCI, difference from VR -40 0 +40 mV Detection voltage H SCIvthH SCI, difference from VR 60 100 140 mV Detection voltage L SCIvthL SCI, difference from VR -140 -100 -60 mV [DEF] Detection voltage DEFvth Difference between LF2 voltage when RFSM = 3.5 V 0.20 0.35 0.50 V Output voltage H DEF-H 4.5 4.9 V Output voltage L DEF-L 0 +0.5 V [APC] Reference voltage LDS LDS voltage at which LDD = 3 V 150 180 210 mV	SLEQ offset	SLEQost	Difference from TO at SLEQ	-30	0	+30	mV
Off VTH SLOFvth SLOF 1.0 1.4 2.0 V [SLC] No signal voltage SLCo SLC 2.25 2.5 2.75 V [Shock] No signal voltage SCIo SCI, difference from VR -40 0 +40 mV Detection voltage H SCIvthH SCI, difference from VR 60 100 140 mV [DEF] Detection voltage L SCIVHL SCI, difference from VR -140 -100 -60 mV [DEF] Detection voltage when RFSM = 3.5 V and DEF is detected and LF2 voltage when RFSM = 3.5 V 0.35 0.50 V Output voltage H DEF-H 4.5 4.9 V Output voltage L DEF-L 0 +0.5 V [APC] Reference voltage LDS LDS voltage at which LDD = 3 V 150 180 210 mV	Offset SLD	SLDost	SLEQ = VR, difference from VR	-100	0	+100	mV
SLC No signal voltage SLCo SLC SLC 2.25 2.5 2.75 V	Offset off	SLDof	Off mode	-40	0	+40	mV
No signal voltage SLCo SLC 2.25 2.5 2.75 V	Off VTH	SLOFvth	SLOF	1.0	1.4	2.0	V
Shock No signal voltage	[SLC]	•		•	•		
No signal voltage	No signal voltage	SLCo	SLC	2.25	2.5	2.75	V
Detection voltage H SCIvthH SCI, difference from VR 60 100 140 mV Detection voltage L SCIvthL SCI, difference from VR -140 -100 -60 mV [DEF] Detection voltage Deference between LF2 voltage when RFSM = 3.5 V and DEF is detected and LF2 voltage when RFSM = NFSM = 3.5 V 0.20 0.35 0.50 V Output voltage H DEF-H 4.5 4.9 V Output voltage L DEF-L 0 +0.5 V [APC] Reference voltage LDS LDS voltage at which LDD = 3 V 150 180 210 mV	[Shock]						
Detection voltage L SCIvthL SCI, difference from VR -140 -100 -60 mV [DEF] Detection voltage Difference between LF2 voltage when RFSM = 3.5 V and DEF is detected and LF2 voltage when RFSM = 3.5 V 0.20 0.35 0.50 V Output voltage H DEF-H 4.5 4.9 V Output voltage L DEF-L 0 +0.5 V [APC] Reference voltage LDS LDS voltage at which LDD = 3 V 150 180 210 mV	No signal voltage	SCIo	SCI, difference from VR	-40	0	+40	mV
DEF	Detection voltage H	SClvthH	SCI, difference from VR	60	100	140	mV
Defection voltage	Detection voltage L	SClvthL	SCI, difference from VR	-140	-100	-60	mV
Detection voltage DEFvth 3.5 V and DEF is detected and LF2 voltage when RFSM = 3.5 V 0.20 0.35 0.50 V Output voltage H DEF-H 4.5 4.9 V Output voltage L DEF-L 0 +0.5 V [APC] Reference voltage LDS LDS voltage at which LDD = 3 V 150 180 210 mV	[DEF]						
Output voltage L DEF-L 0 +0.5 V [APC] Reference voltage LDS LDS voltage at which LDD = 3 V 150 180 210 mV	Detection voltage	DEFvth	3.5 V and DEF is detected and LF2 voltage when	0.20	0.35	0.50	V
Output voltage L DEF-L 0 +0.5 V [APC] Reference voltage LDS LDS voltage at which LDD = 3 V 150 180 210 mV	Output voltage H	DEF-H		4.5	4.9		V
[APC] LDS LDS voltage at which LDD = 3 V 150 180 210 mV	Output voltage L	DEF-L			0	+0.5	V
· · · · · · · · · · · · · · · · · · ·		•					
Off voltage LDDof LDD 3.9 4.3 4.6 V	Reference voltage	LDS	LDS voltage at which LDD = 3 V	150	180	210	mV
	Off voltage	LDDof	LDD	3.9	4.3	4.6	V

Pin Function

Descriptions enclosed in brackets apply to the LA9231M only.

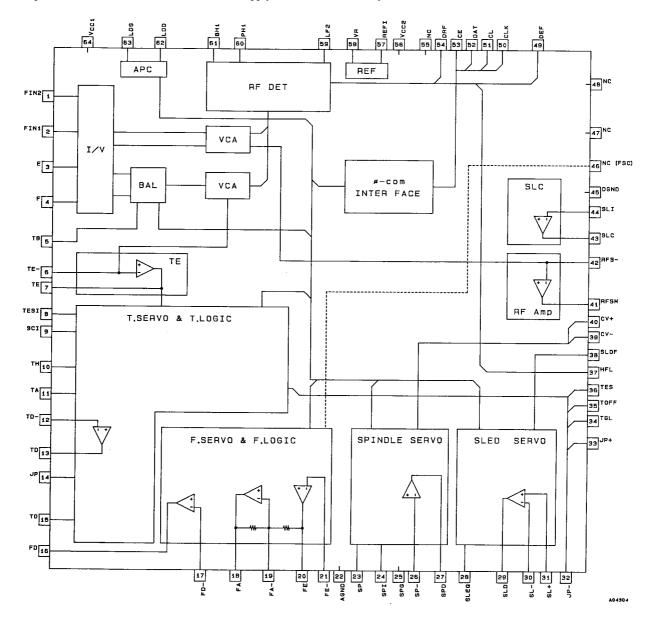
Pin No.	Symbol	Contents
1	FIN2	Pickup photodiode connection pin. Added to FIN1 pin to generate the RF signal, subtracted from FIN1 pin to generate the FE signal.
2	FIN1	Pickup photodiode connection pin.
3	E	Pickup photodiode connection pin. Subtracted from F pin to generate the TE signal.
4	F	Pickup photodiode connection pin.
5	ТВ	TE signal DC component input pin.
6	TE-	Pin which connects the TE signal gain setting resistor between this pin and TE pin.
7	TE	TE signal output pin.
8	TESI	TES (Track Error Sense) comparator input pin. The TE signal is input through a bandpass filter.
9	SCI	Shock detection input pin.
10	TH	Tracking gain time constant setting pin.
11	TA	TA amplifier output pin.
12	TD-	Pin for configuring the tracking phase compensation constant between the TD and VR pins.
13	TD	Tracking phase compensation setting pin.
14	JP	Tracking jump signal (kick pulse) amplitude setting pin.
15	TO	Tracking control signal output pin.
16	FD	Focusing control signal output pin.
17	FD-	Pin for configuring the focusing phase compensation constant between the FD and FA pins.
18	FA	Pin for configuring the focusing phase compensation constant between the FD ⁻ and FA ⁻ pins.
19	FA ⁻	Pin for configuring the focusing phase compensation constant between the FA and FE pins.
20	FE	FE signal output pin.
21	FE-	Pin which connects the FE signal gain setting resistor between this pin and FE pin.
22	AGND	Analog signal GND.
23	SP	CV ⁺ and CV ⁻ pins input signal single-end output.
24	SPI	Spindle amplifier input.
25	SPG	12-cm spindle mode gain setting resistor connection pin.
26	SP-	Spindle phase compensation constant connection pin, along with the SPD pin.
27	SPD	Spindle control signal output pin.
28	SLEQ	Sled phase compensation constant connection pin.
29	SLD	Sled control signal output pin.
30	SL ⁻	Input pin for sled movement signal from microprocessor.
31	SL ⁺	Input pin for sled movement signal from microprocessor.
32	JP-	Input pin for tracking jump signal from DSP.
33	JP ⁺	Input pin for tracking jump signal from DSP.
34	TGL	Input pin for tracking gain control signal from DSP. Gain is low when TGL is high.
35	TOFF	Input pin for tracking off control signal from DSP. Tracking servo is off when TOFF is high.
36	TES	Output pin for TES signal to DSP.
37	HFL	The High Frequency Level is used to determine whether the main beam is positioned over a bit or over the mirrored surface.
38	SLOF	Sled servo off control input pin
39	CV-	Input pin for CLV error signal from DSP.
40	CV ⁺	Input pin for CLV error signal from DSP.
41	RFSM	RF output pin.
42	RFS ⁻	RF gain setting and EFM signal 3T compensation constant setting pin, along with the RFSM pin.
43	SLC	Slice Level Control is an output pin that controls the data slice level used by the DSP for the RF waveform.
44	SLI	Input pin used by DSP for controlling the data slice level.
45	DGND	Digital system GND pin.
46	NC	No connection
	[FSC]	[Focus search smoothing capacitor output pin.]
47	NC	No connection
48	NC	No connection
49	DEF	Disc defect detection output pin.
50	CLK	Reference clock input pin. 4.23 MHz signal from the DSP is input.
51	CL	Microprocessor command clock input pin.

Continued from preceding page.

Pin No.	Symbol	Contents
52	DAT	Microprocessor command data input pin.
53	CE	Microprocessor command chip enable input pin.
54	DRF	RF level detection output (Detect RF).
55	NC	No connection
56	V _{CC} 2	Servo system and digital system V _{CC} pin.
57	REF1	By-pass capacitor connection pin for reference voltage.
58	VR	Reference voltage output pin.
59	LF2	Disc defect detection time constant setting pin.
60	PH1	RF signal peak hold capacitor connection pin.
61	BH1	RF signal bottom hold capacitor connection pin.
62	LDD	APC circuit output pin.
63	LDS	APC circuit input pin.
64	V _{CC} 1	RF system V _{CC} pin.

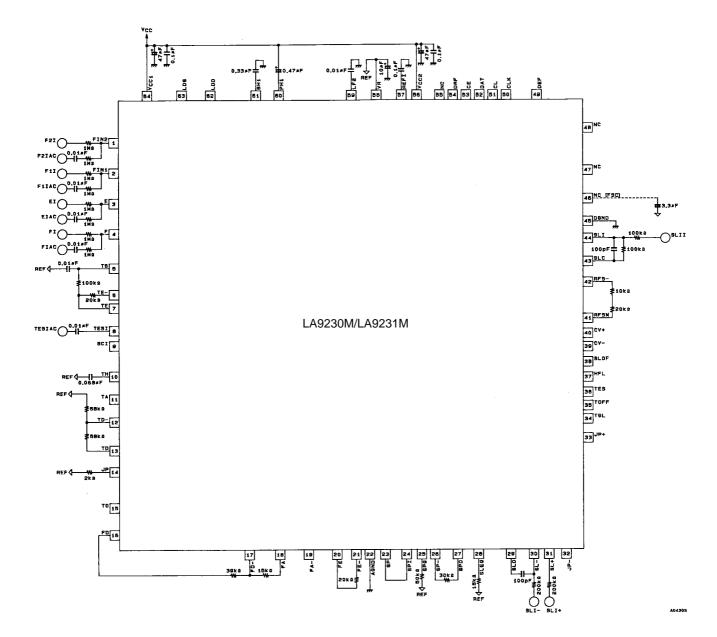
Equivalent Circuit Block Diagram

Descriptions enclosed in dotted lines or brackets apply to the LA9231M only.



Test Circuit

Descriptions enclosed in dotted lines or brackets apply to the LA9231M only.



Description of Operation

1. APC (auto laser power control)

This circuit controls the pickup laser power. The laser is turned on and off by commands from the microprocessor.

2. RF amplifier (eye pattern output)

The pickup photodiode output current (A + C) is input to FIN2 (pin 1), and (B + D) is input to FIN1 (pin 2). The current that is input is converted to the voltage, passes through the AGC circuit, and is then output from the RFSM amplifier output RFSM (pin41). The internal AGC circuit has a variable range of ± 3 dB, and the time constant can be changed through the external capacitor connected to PH1 (pin 60). In addition, this circuit also controls the bottom level of the EFM signal (RFSM output), and the response can be changed through the external capacitor connected to BH1 (pin 61). The center gain setting for the AGC variable range is set by the resistance between RFSM (pin 41) and RFS⁻ (pin 42); if necessary, this resistance is also used for 3T compensation for the EFM signal.

3. SLC (slice level control)

The SLC sets the duty ratio for the EFM signal that is input to the DSP to 50%. The DC level is determined by integrating the EFMO signal output from the DSP to determine the duty factor.

4. Focus servo

The focus error signal is derived by detecting the difference between (A+C) and (B+D), which is (B+D)-(A+C), and is then output from FE (pin 20). The focus error signal gain is set by the resistance between FE (pin 20) and FE $^-$ (pin 21). The FA amplifier is the pickup phase compensation amplifier, and the equalizer curve is set by the external capacitor and resistance. Furthermore, this amplifier has a mute function which is applied when V_{CC} is turned on, when the F-SERVO OFF command is sent, and during F-SEARCH. In order to turn the focus servo on, send either the LASER ON command or the F-SERVO ON command.

The FD amplifier has a phase compensation circuit, a focus search signal composition function, and an offset cancellation function. Focus search is initiated by the F-SEARCH command, and a ramp waveform is generated by the internal clock. This waveform is used for focus detection (focus zero cross) with the focus error signal and then turn the focus servo on. The ramp waveform amplitude is set by the resistance between FD (pin 16) and FD⁻ (pin 17). Offset cancellation cancels the IC offset; adjustment is started by the FOCUS-OFFSET ADJUST START command, and is completed in about 250 ms. To cancel even the offset for the IV amplifier, etc., it is necessary to send the F-SERVO ON (LASER OFF) command. The FOCUS-OFFSET ADJUST OFF command is used to return to the state prior to offset cancellation.

For the LA9231M, FCS (pin 46) is for smoothing the focus search ramp waveforms, and a capacitor is connected between FSC and VR.

5. Tracking servo

The pickup photodiode output current is input to E (pin 3) and F (pin 4). The current that is input is converted to the voltage, passes through the balance adjustment VCA circuit and then the VCA circuit that follows the gain in the RFAGC circuit, and is then output from TE (pin 7). The tracking error gain is set by the resistance between TE⁻ (pin6) and TE (pin7). The TA output (pin 11) has a built-in resistance to allow configuration of a low-pass filter.

The TH amplifier alters the servo response characteristics according to the THLD signal, etc., generated internally after detection of the TGL signal from the DSP or the JP signal. When a defect is detected, the THLD mode goes into effect internally. To avoid this, short DEF (pin 49) to L = GND. By inserting an external bandpass filter to remove the shock component from the tracking error signal at SCI (pin 9), the gain is automatically boosted when a defect is detected. The TD amplifier performs servo loop phase compensation; the characteristics are set by external CR. Furthermore, this amplifier has a mute function, which is applied when V_{CC} is turned on or the TRACK-SERVO OFF command is issued. The muting function is released by the TRACK-SERVO ON command.

The TOFF amplifier that is positioned immediately after TD (pin 13) functions to turn off the servo in response to the TOFF signal from the DSP.

The TO amplifier has a JP pulse composition function and a tracking offset cancellation function. The JP pulse is set by JP (pin 14). (THLD detection is performed internally.) Offset cancellation is completed in about 30 ms. The TRACK-SERVO ON command and setting the TOFF pin (pin 35) low are required for offset cancellation.

Note:

The LC78620E TOFF ON/OFF command is valid only when disc motor control is in CLV mode. Accordingly, tracking offset is cancelled in normal CLV mode. Note that when performed in STOP mode, external control of the TOFF pin is required.

6. Sled servo

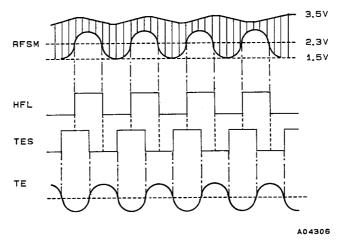
The response characteristics are set by SLEQ (pin 28). The amplifier positioned after SLEQ (pin 28) has a mute function that is applied either when SLOF (pin 38) goes high or the SLED OFF command is issued. The sled is moved by inputting current to SL^- (pin 30) and SL^+ (pin 31); specifically, the pins are connected to the microprocessor output ports via resistors, and the movement gain is set by the resistance value of that resistor. It is important to note that if there is a deviation in the resistance values for SL^- (pin 30) and SL^+ (pin 31), an offset will arise in the SLD output.

7. Spindle servo

The Configures this servo circuit, which maintains the linear velocity of the disc at a constant speed, along with the DSP. This circuit accepts signals from the DSP through CV^- (pin 39) and CV^+ (pin 40) and sets the equalizer characteristics through SP (pin 23), SP $^-$ (pin 36), and SPD (pin 27), which are output to SPD (pin 27). The 12-cm mode amplifier gain is set by the resistor connected between SPG (pin 25) and the reference voltage. In 8-cm mode, this amplifier serves as an internal buffer, and SPG (pin 25) is ignored. Note that the gain setting is made for 8-cm mode first, and then 12-cm mode. If SPG (pin 25) is left open, the gain is forcibly set for 8-cm mode, regardless of whether 8-cm or 12-cm mode is in effect.

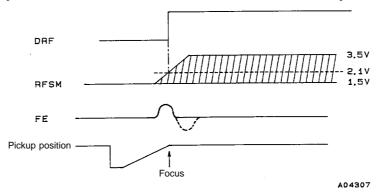
8. TES and HFL (traverse signals)

When moving the pickup from the outer track to the inner track, the EF output from the pickup must be connected so that the phase relationship of TES and HFL is as shown in the diagram below. For the TESI input, the TES comparator has negative polarity and hysteresis of approximately ± 100 mV. An external bandpass filter is needed in order to extract only the required signal from the TE signal.



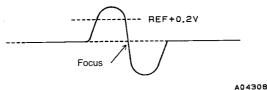
9. DRF (luminous energy determination)

DRF goes high when the peak of the EFM signal (RFSM output) held by the PH1 (pin 60) capacitor exceeds approximately 2.1 V. The PH1 (pin 60) capacitor affects the DRF detection time constant and the RFAGC response bidirectional setting.



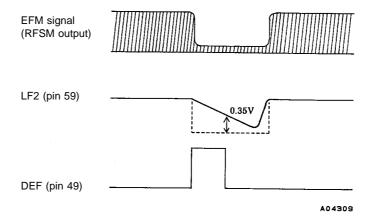
10. Focus determination

Focus is assumed to be obtained when the focus error signal S curve reaching REF \pm 0.2 V is detected, and the S curve subsequently returns to REF.



11. DEFECT

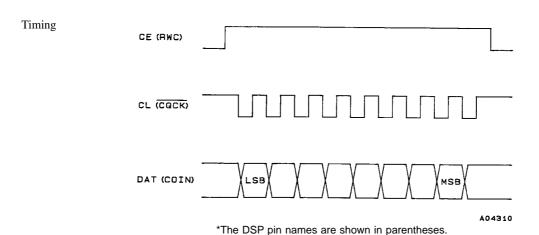
The mirrored surface level is maintained by the capacitor for LF2 (pin 59); when a drop in the EFM signal (RFSM output) reaches 0.35~V or more, a high signal is output to DEF (pin 49). If DEF (pin 49) goes high, the tracking servo enters THLD mode. In order to prevent the tracking servo from entering THLD mode when a defect is detected, prevent DEFECT from being output by either shorting DEF (pin 49) to GND, or shorting LF2 (pin 59) to GND. The DEFECT output is driven by constant current (approximately $100~\mu$ A).



12. Microprocessor interface

Because the Reset (Nothing) command initializes the LA9230M and the LA9231M, it must be used carefully. The LA9230M/LA9231M command acceptance (mode switching) timing is defined by the internal clock (4.23 MHz divided to 130 kHz) after the falling edge of CE (RWC); therefore, when commands are sent consecutively, CE must go low for at least $10 \text{ }\mu\text{sec.}$ / The 4.23 MHz clock is required for that reason. 2BYTE-COMMAND DETECT and 2BYTE-COMMAND RESET are used only for the purpose of masking two-byte data.

All instructions can be input by setting CE high and sending commands synchronized with the CL clock from the microprocessor to DAT (pin 52) in LSB first format. Note that the command is executed at the falling edge of CE.



13. Reset circuit

The power-on reset is released when V_{CC} exceeds approximately 2.8 V.

14. Pattern design notes

To prevent signal jump-in from CV⁺ (pin 40) to RFSM (pin 41), a shielding line is necessary in between.

15. V_{CC} /REF/GND/NC

V_{CC}1 (pin 64) : RF system

V_{CC}2 (pin 56) : SERVO system, DIGITAL system AGND (pin 22) : RF system, SERVO system

DGND (pin 45) : DIGITAL system NC (pins 46*, 47, 48, and 55) : No connection

*Only for LA9230M

Microprocessor Command List

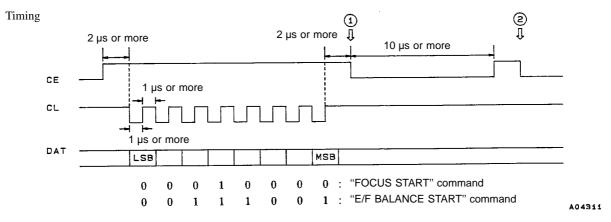
MSB LSB	Command	Reset mode Power on mode	DSP
0000000	RESET		RESET(NOTHING)
00001000	FOCUS START		FOCUS START #1
11110000 111111000 11111111	2BYTE-COMMAND DETECT 2BYTE-COMMAND DETECT 2BYTE-COMMAND RESET		2BYTE-COMMAND DETECT 2BYTE-COMMAND DETECT 2BYTE-COMMAND RESET
10010000	FOCUS-OFFSET ADJUST START		_
10010001	FOCUS-OFFSET ADJUST OFF	0	_
10010010	TRACK-OFFSET ADJUST START		_
10010011	TRACK-OFFSET ADJUST OFF	0	_
10010100	LASER ON LASER OFF : F-SERVO ON		_
10010110	LASER OFF : F-SERVO OFF	0	_
10010111	SPINDLE 8CM		_
10011000	SPINDLE 12 CM	0	_
10011001	SPINDLE OFF		_
10011010	SLED ON	0	_
10011011	SLED OFF		_
10011100	E/F BALANCE START	Nonadjusted	_
10011101	TRACK-SERVO OFF	0	_
10011110	TRACK-SERVO ON		_

Notes Concerning Microprocessor Program Creation

1. Commands

After sending the FOCUS START command and the E/F BALANCE START command, send 11111110 (FEH) in order to clear the internal registers of the IC.

Reason: Although the above commands are executed at point ① in the timing chart below, the same commands will be executed again at point ② if there is subsequent input to CE as shown below.



When sending a TRACK-OFFSET ADJUST START command or a FOCUS-OFFSET ADJUST START command after either $V_{\rm CC}$ ON (POWER ON RESET), RESET command, or a corresponding OFFSET ADJUST OFF command, waiting time is necessary as listed below. (Only when a 4.2 MHz clock is input.)

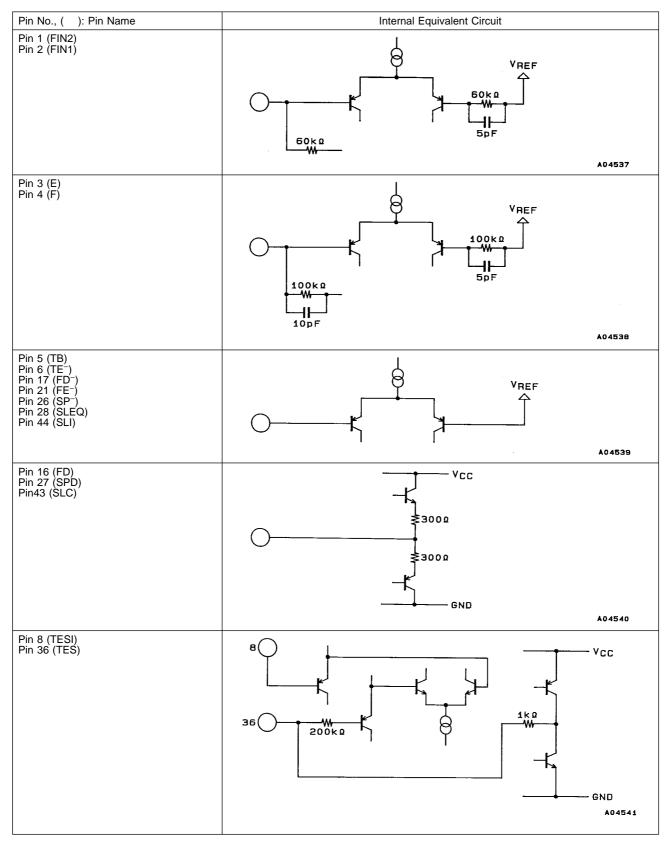
TRACK-OFFSET ADJUST START: 4 ms or more FOCUS-OFFSET ADJUST START: 30 ms or more

2. E/F balance adjustment

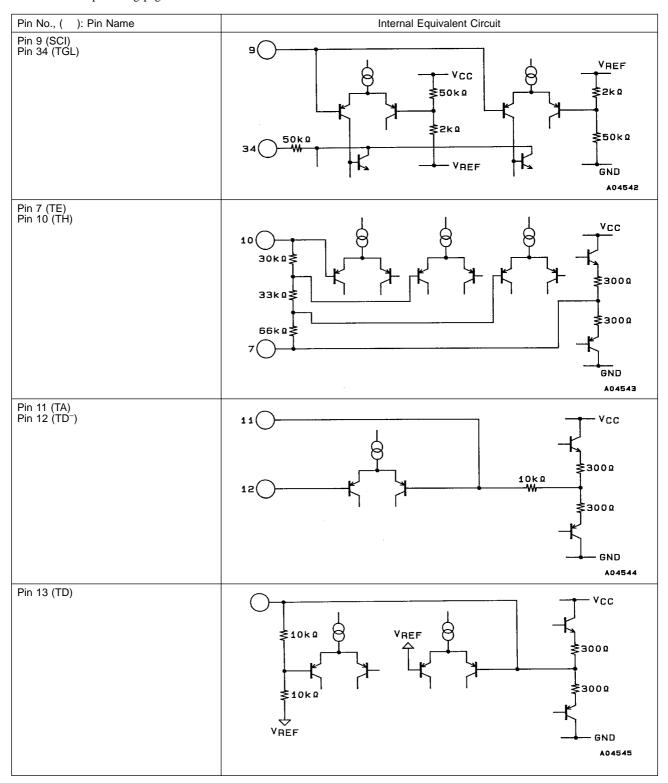
E/F balance adjustments should be made in a bit region of the disc, not a mirrored region. (This is because the E/F balance adjustment entails about 100 to 200 track kicks.)

Since there is no track-kick for LA9231M, measures must be taken during EF balance adjustment to obtain a stable TE signal. (By a sled movement signal from a microprocessor, for example.)

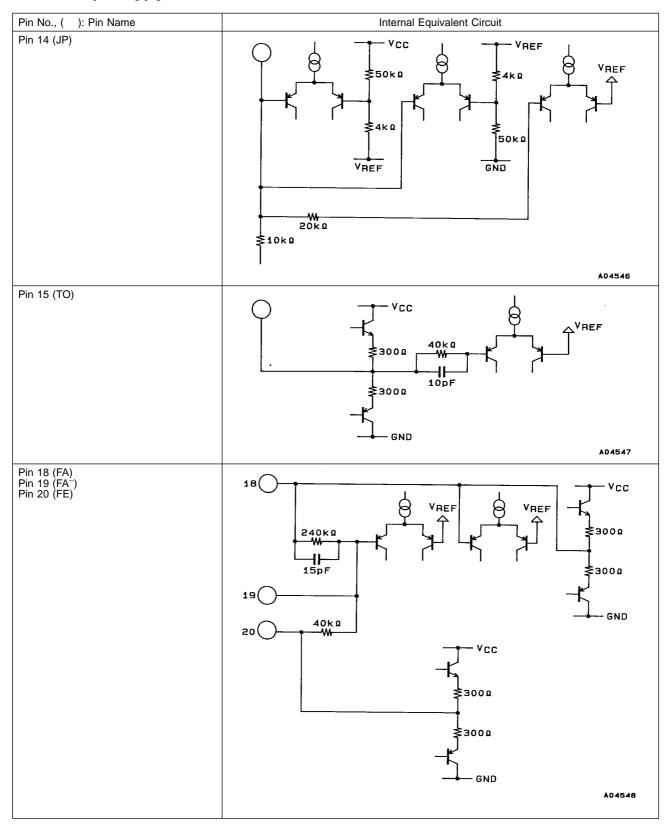
Pin Internal Equivalent Circuit



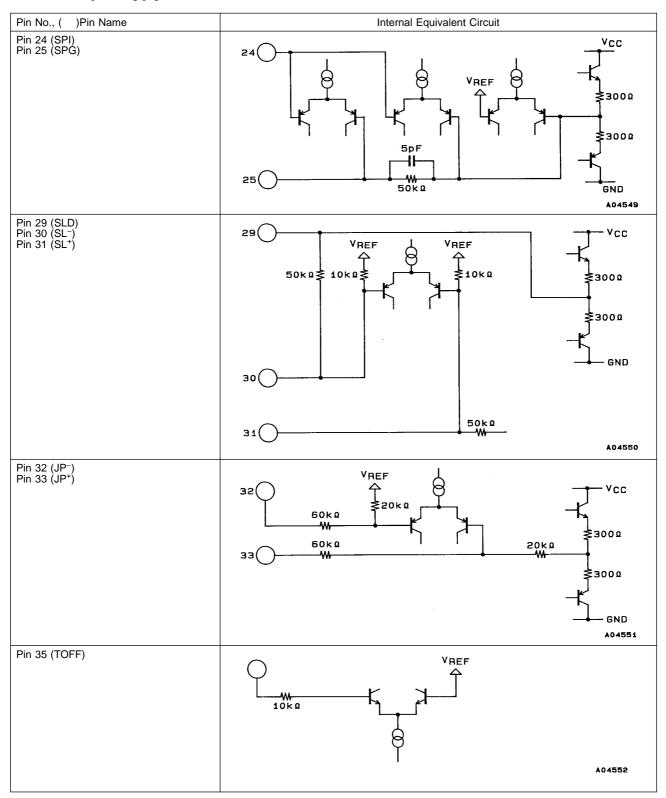
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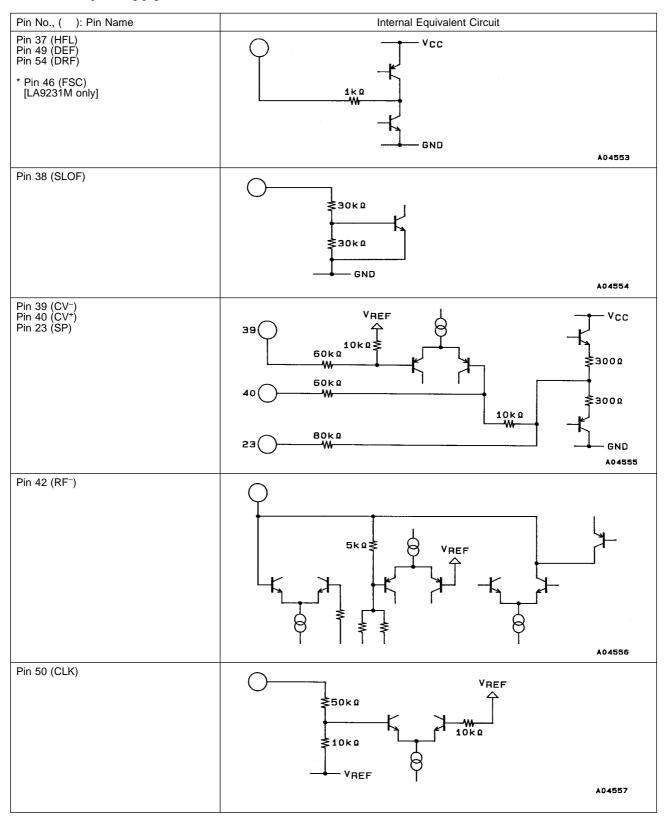
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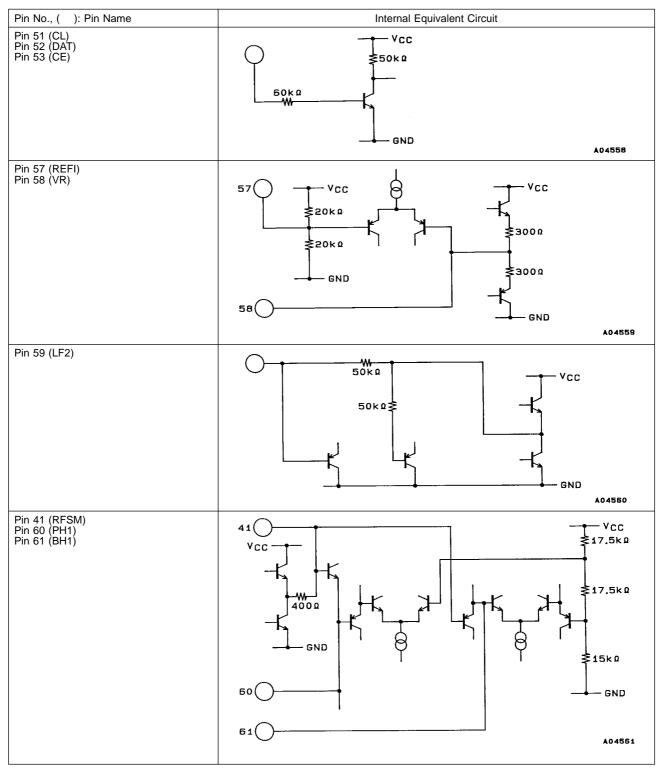
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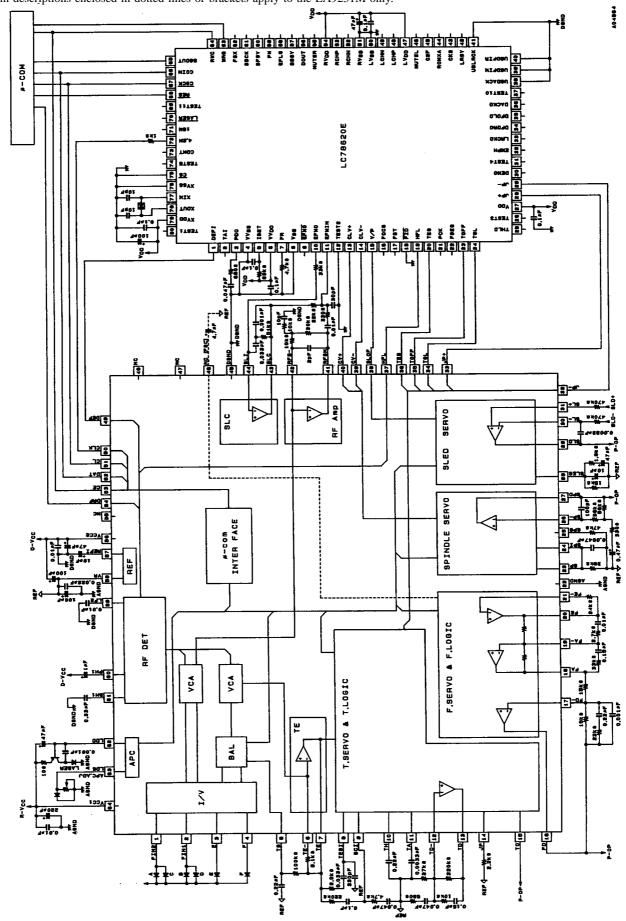


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Pin No., (): Pin Name	Internal Equivalent Circuit	
Pin 62 (LDD)	VCC -	
Pin 63 (LDS)	A04563	

Sample Application Circuit

Pin descriptions enclosed in dotted lines or brackets apply to the LA9231M only.



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